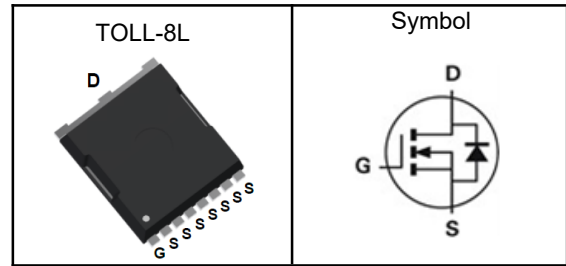


N-Channel Enhancement Mode MOSFET
Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Applications

- Power Management in Desktop Computer
- DC/DC Converters

Pin Description


V_{DSS}	150	V
$R_{DS(ON)-Typ}$	6.0	m Ω
I_D	140	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	150	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	W
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.5mH	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.5mH	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	60	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.5	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 $^\circ\text{C}$.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



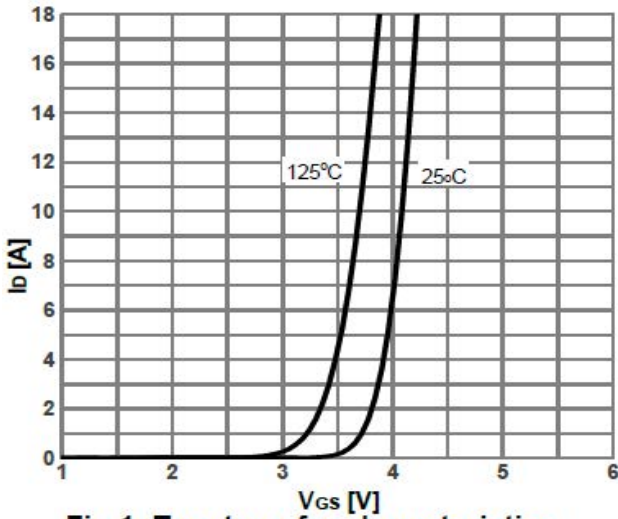
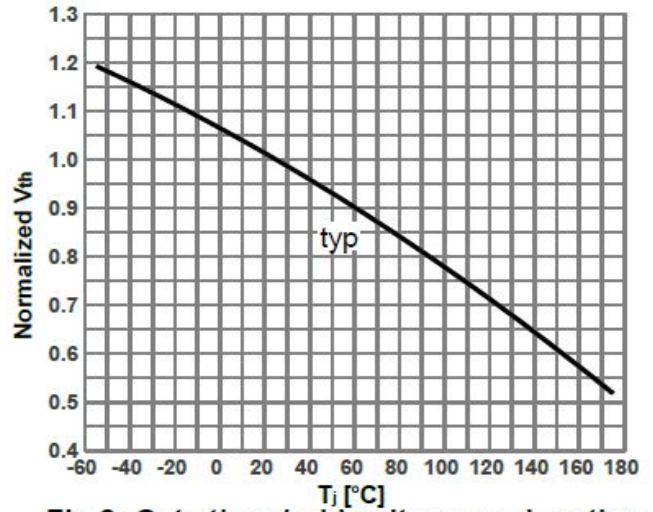
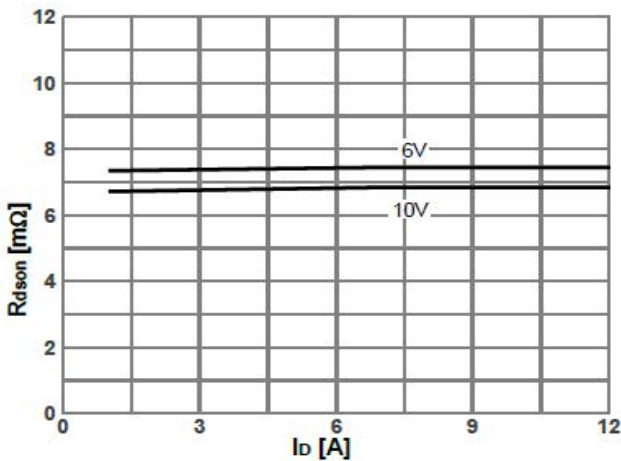
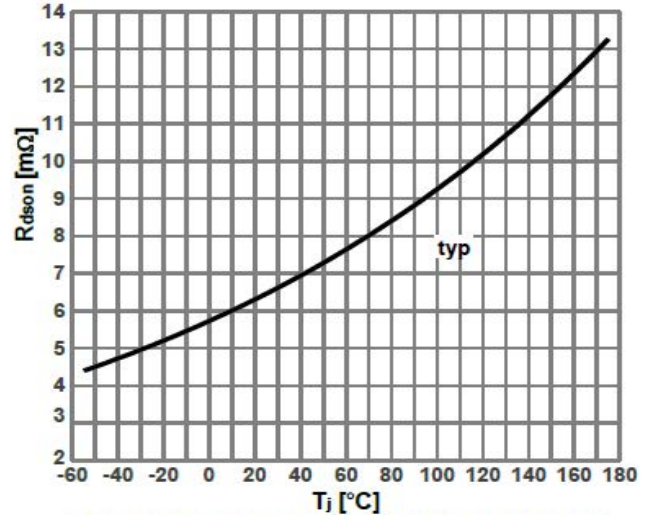
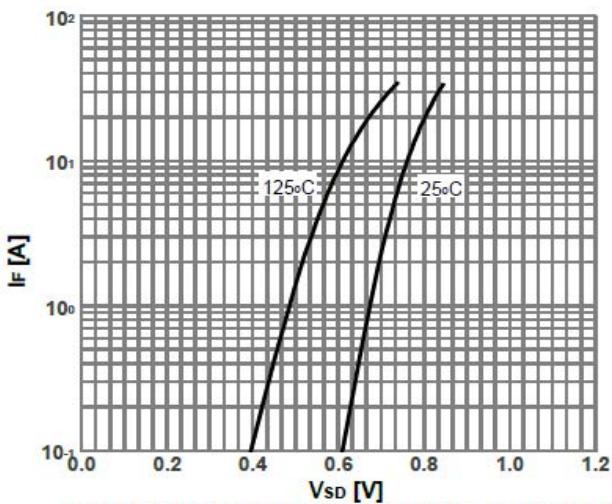
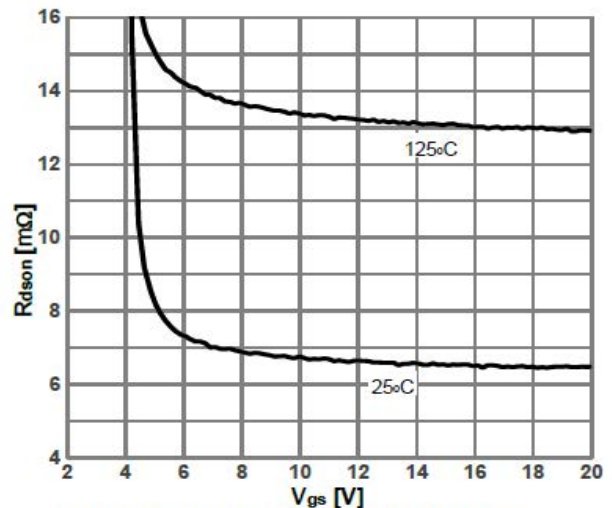
N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$	---	---	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	---	4	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=20A$	---	6.0	7.2	$m\Omega$
		$V_{GS}=6V, I_D=10A$	---	7.2	10	$m\Omega$
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=75V, \text{Freq.}=1\text{MHz}$	---	5200	---	pF
C_{oss}	Output Capacitance		---	410	---	
C_{rSS}	Reverse Transfer Capacitance		---	10	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DD}=75V, I_D=100A, R_G=1.6\Omega$	---	22	---	nS
T_r	Turn-on Rise Time		---	110	---	
$T_{d(off)}$	Turn-off Delay Time		---	44	---	
T_f	Turn-off Fall Time		---	100	---	
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DD}=75V, I_D=20A$	---	72	---	nC
Q_{gs}	Gate-Source Charge		---	18	---	
Q_{gd}	Gate-Drain Charge		---	10	---	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	$I_S=10A, V_{GS}=0V$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=100A, V_R=75V, di_F/dt=100A/\mu s$	---	45	---	nS
Q_{rr}	Reverse Recovery Charge		---	12	---	nC

Note ④: Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤: Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET
Typical Characteristics

Fig 1: Typ. transfer characteristics

Fig 2: Gate threshold voltage vs. Junction temperature

Fig 3: On-state resistance vs. Drain current

Fig 4: On-state resistance vs. Junction temperature

Fig 5: Forward characteristics of reverse diode

Fig 6: On-state resistance vs. Vgs characteristics

N-Channel Enhancement Mode MOSFET

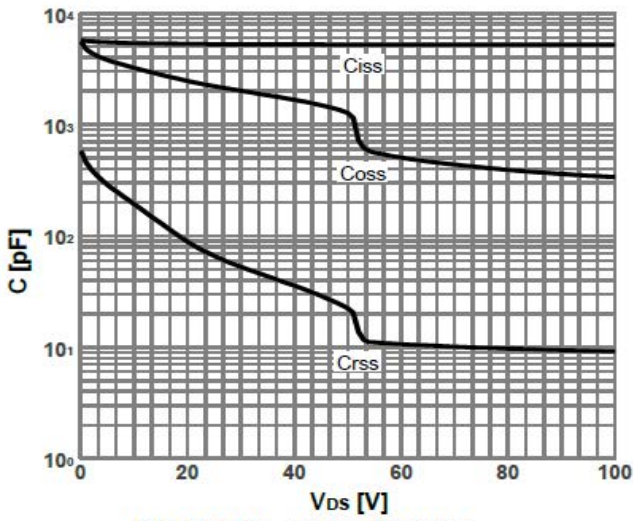


Fig 7: Typ. capacitances

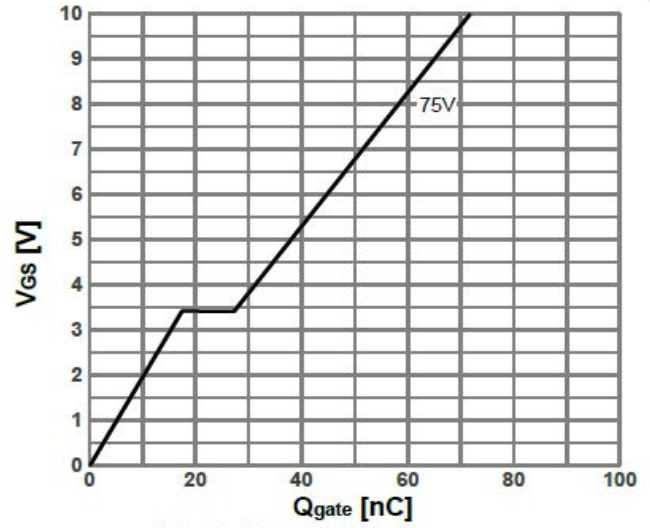


Fig 8: Typ. gate charge

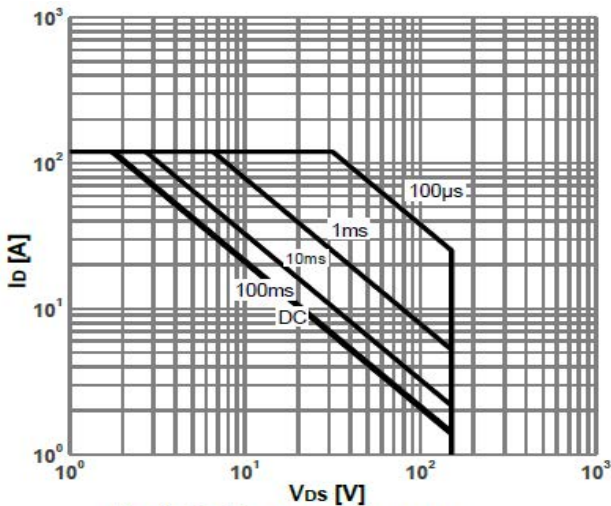


Fig 9: Safe operating area

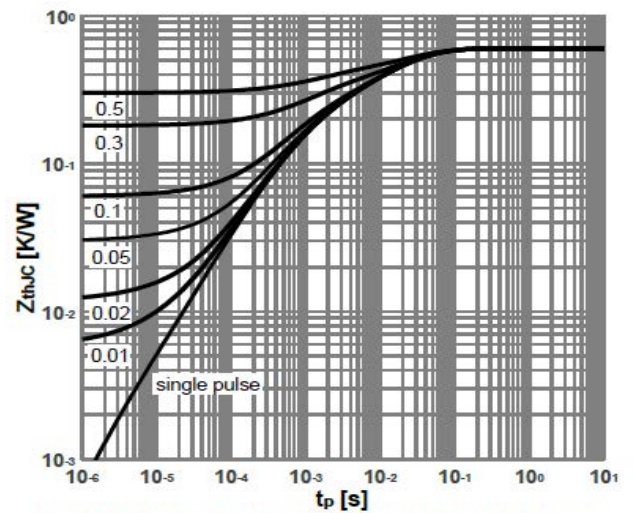
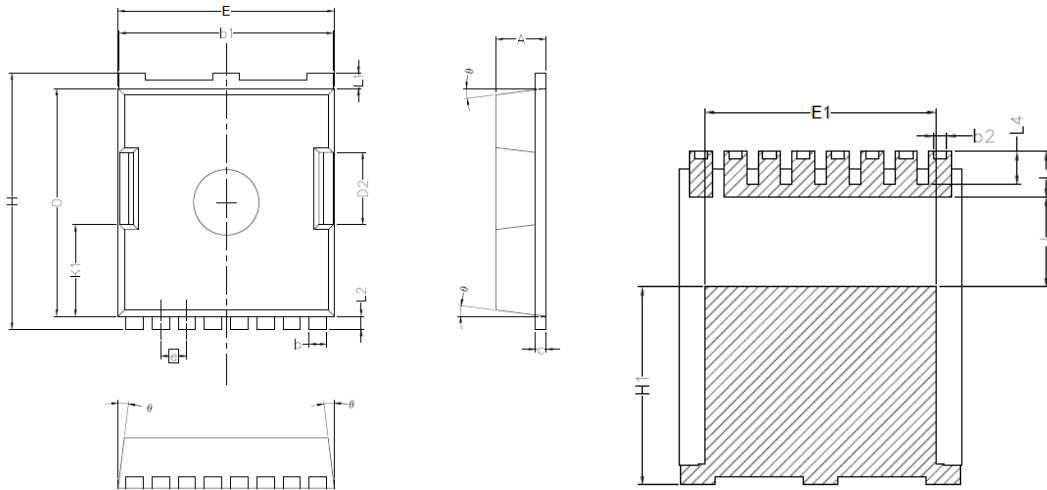


Fig 10: Max. transient thermal impedance

N-Channel Enhancement Mode MOSFET
TOLL-8L Package Outline Data


Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.20	2.40
b	0.70	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.60
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°